































中国第三届 PICTIG 技术年会 ATCA/PXI The 3rd China Annual PICMG Tech-forum Service Providers Pilot Modular

<u>Architectures</u>

Telefonica I+D and Intel sign a Collaboration Agreement under the Terms of which Telefonica I&D will use Intel® Techology to Develop Solutions for the Telecoms Market -Madrid, October 16 2003

KT and Intel to Jointly Develop Next Generation Network Pilot System based on Intel's Modular Communication Platform - Seoul, Korea, Dec 15, 2003

intal

NTT Joins OSDL World's largest telecommunications company joins Linux consortium to accelerate development of Linux for enterprise datacenters and carrier grade applications Beaverton, OR and Tokyo, February 3, 2004







